ABSTRACT

# DROP-MOLD CONFORMABLE MATERIAL AS AN ENCAPSULATION FOR AN INTEGRATED CIRCUIT PACKAGE SYSTEM AND METHOD FOR MANUFACTURING THEREOF

A method for manufacturing an integrated circuit package system includes: providing an integrated circuit; mounting a lead on the periphery of the integrated circuit; connecting the integrated circuit to the lead with an interconnect; and forming a conformable material by pressing the conformable material on the integrated circuit, the lead, and the interconnect

(Fig, 2)